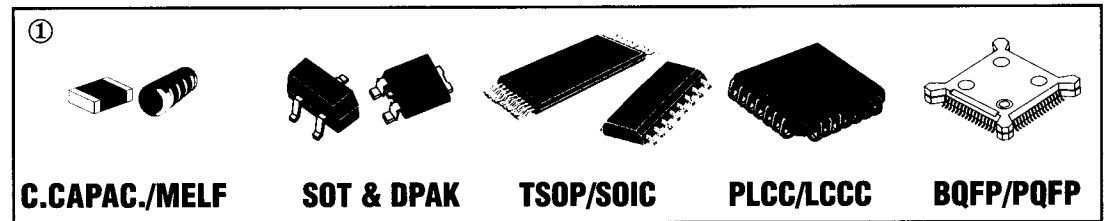
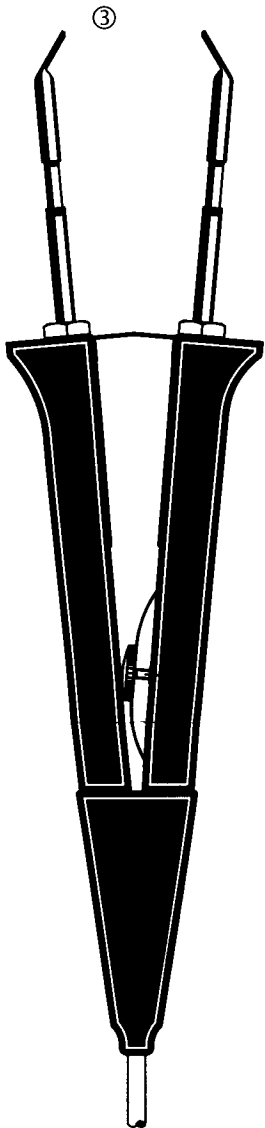


Process description: SMD REMOVAL

using conductive
tweezer

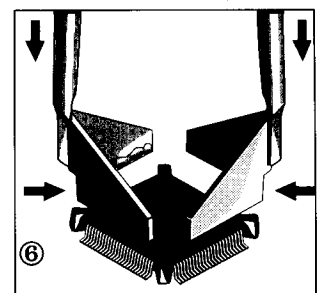
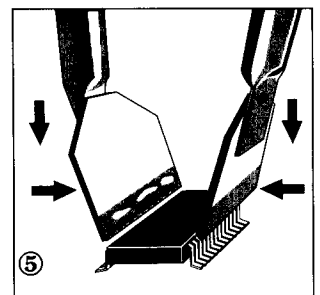


②

SMT UNIT 60 A / SMT-UNIT 60 AS (Pincette 40)				SMT-UNIT 60 A (Micro tool)
422 ED - SOT 8	422 FD3 - SOT 12	422 FD1 - SOT 16	422 FD4 - SOT 20	212 BD
422 FD2 - SOT 24	422 FD5 - SOT 28	422 FD6 - SOT 32	422 FD7 - SOT 40	212 CD
422 QD5 - PLCC 20	422 QD1 - PLCC 28	422 QD6 - TQFP 80T25	422 QD3 - PLCC 44	212 ED
422 QD4 - PLCC 52	422 QD2 - PLCC 68	422 QD7 - PLCC 84	422 QD9 - BQFP 100	212 KD
422 QD8 - BQFP 132	422 RD1 - QFP 100	422 RD2 - PLCC 32	422 MD-MELF's u. MINIMELF's	212 MS

Process Description:

1. Select proper tip ② from SMD 8012 tip holder to match component type ①. Install in Pincette 40 removal tweezer ③ and align.
2. Set temperature to 300 °C (572°F) - 320 °C (608°F) using the temperature table included with your tweezer ④.
3. Apply solder to the inside pre-tinneable portion of the tip until a small bath of solder is formed. Solder should not drop from tip!
4. Apply flux to component being removed.
5. Holding the Pincette 40 gently in your hand and perpendicular to the PCB, lower the tip down onto the soldered connections of the SMD ⑤⑥.

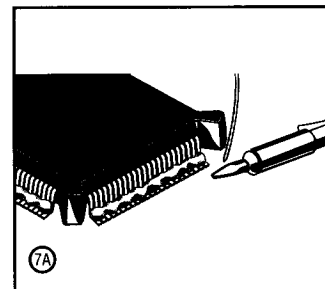


④

Tip	ED	FD 1	FD 2/3	FD 4	FD 5	FD 6/7	MD	RD 1	RD 2	RD 3/4	RD 5/6	RD 7
1	375	365	320	345	400	330	310	330	300	285		
2	420	400	375	400	465	390	355	375	345	330		
3	510	475	440	465	555	465	420	445	415	375		
4	510	525	510	510	560	530	500	525	505	475		
5	610	680	645	625	750	635	565	555	510	510		
6	675	715	655	660	805	690	610	645	590	545		
7	780	715	660	675	830	715	630	665	610	565		
8	885	835	840	805	985	815	735	780	725	680		

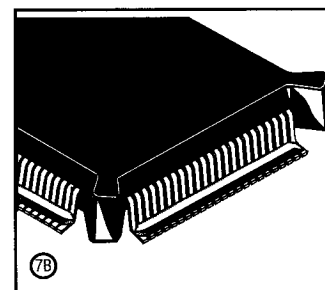
Temperature table
desoldering inserts (°F)

6. Gently close the tweezer into the body of the SMD and push lightly down onto the PCB, making sure all pins are contacted with the tip. This closing and pushing motion effectively transfers the heat to all sides of the SMD and should allow the SMD to be safely removed within 1-3 seconds ⑤⑥.



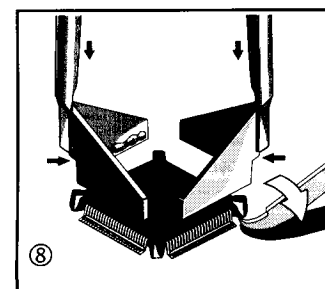
7. If SMD is not removed after 3 seconds DO NOT USE FORCE!
Release SMD from tweezer.

8. Repeat steps 3 and 6. If SMD is still not removed DO NOT USE FORCE!
Release SMD from tweezer.



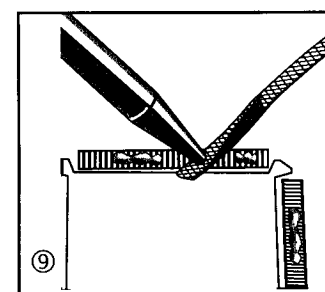
9. Prepare the SMD for better thermal transfer by connecting pins on all sides of the SMD with solder. We recommend the bridge technique ⑦A or the wire wrap technique ⑦B

10. Repeat step 3 and 6. If SMD is still not removed DO NOT USE FORCE!
Release SMD from tweezer: SMD may be glued.



11. Repeat step 9. Use a curved, needle nose tweezer to create a lever under one corner of the glued SMD. Repeat steps 3 and 6 while simultaneously pushing down on the tweezer ⑧.
This diagonal force will break most of the hardest glue points.

12. Remove old solder from pads using Ersa Wick ⑨ and clean.



13. You are now ready to re-install new SMD. For fine-pitch SMDs see Ersa Process description: FINE-PITCH Installation.



Recommended equipment (alternative):

Type	Order-no.
SMT UNIT 60 A/	SMT 60 A/
SMT UNIT 60 AS	SMT 60 AS
Rework 80	RW 8000
VAC-Pen or SMD-Vampir	VP 100 / SVP 100
ERSA MicroWell Tip	212 MS
Solder Wick	NC 1,5/10
Solder Wick	NC 2,2/10



Accessories:

Type	Order-no.
Flux cream	FMKANC 32-005
Solder wire	15MM0100HF
Flux removal and cleaning set	RPC 100 u. RTG 100

**Complete product information is available upon request.
Call us today and take your first step into THE NEW DIMENSION.**